# Record of Letter Ballot Review by TC Chapter for Procedural Review

Region/Locale: North America

Global Technical Committee: Physical Interfaces & Carriers TC Chapter Cochairs: Matt Fuller (Entegris), Melvin Jung (Intel)

Standards Staff: Laura Nguyen

	Scheduled in Background Statement	Actual
Date	07/10/2019	07/10/2019
Location	Moscone Center, San Francisco, CA	Moscone Center, San Francisco, CA
Reason for		
Change of		
Date and/or		
Location		
(if changed)		

Note: See *Regulations* ¶ 9.5 Exceptions for allowable reason to change.

### I. Document Number and Title

<b>Document Number</b>	Document Title
6311A	New Standard: SPECIFICATION FOR TEM LAMELLA
	CARRIERS USED IN ELECTRON MICROSCOPY
	WORKFLOWS

# II. Tally

Standards staff to fill in.

Voting Tally: As-cast tally after close of voting period

Note: A minimum of 60% of the Voting Interests that have TC Members within the global technical committee that issued the Letter Ballot must return Votes. (*Regulations* ¶ 9.6.2.1.1)

#### Voting Tally (with example values):

Voting Interest:	Returned Votes		Distribution		Return Rate	
Letter Ballot	55	÷	83	=	66.3%	≥60%
Intercommittee Ballot	44	]				
Voting Interest Reject(s)	1		Total	Vote	rs with Rejects	1
Voting Interest Accept(s)	37					

Note: See *Regulations* § 3.2.1 for definition of Voting Interest.

# III. Rejects

# Voting Interest Reject 1 (Voting Interest Name: TEL) Voter Reject 1 (Voter: Supika Mashiro/Tokyo Electron Ltd.) Negative 1

9	ative i						
	Referenced Section/		TC Chapter to fill in, including	text in the ballot if nec	essary.		
	Paragraph	Section 7					
Negative		*Original complete Negative text (e.g., issue, justification, suggestion) should be copied.					
ative	Negative Text	the info	usage of footnotes in section 7 is ootnote doesn't provide reference mation. They should be expresse anation by a description in NOTE ems the TF leader/author confuse.	e to outside SEMI mater ed by using NOTE follow i.	ial or trademark owner ring each section needs an		
TF	input (optional)						
	Withdrawal	X	No Negative withdrawal made by	y Voter.	GO TO "Related" subsection		
	(check one)		Withdrawal document received by MM/DD/YYYY.	by Standards staff on	GO TO "Final" subsection → (A)		
	Motion and	X	'Related' is mutually agreed upo	n. (Needs no motion.)	GO TO "Persuasive" subsection		
	Reason (check one)		Negative is not related. (Needs	≥2/3 votes to pass.)			
			Reason XXXX				
Rel	Motion by/ 2 <sup>nd</sup> by	Name (Company)/Name (Company)					
Related	Discussion						
		XX	Y-XX N; Motion passed/failed.				
	Result of Vote (check one)		[Negative is not related.] < 2/3		GO TO "Persuasive" subsection		
	(61100110)		2/3 ≤ [Negative is not related.]		GO TO "Final" subsection → (B)		
			Negative is related and persuasi	ve. (Needs >1/3 votes t	to pass.)		
Pe	Motion and Reason (check one)	X	Negative is related and not persuasive. (Needs ≥2/3 vo		etes to pass.)		
Persuasive	(5.155).		Reason The issue	e can be resolved by an	editorial change.		
ive	Motion by/ 2 <sup>nd</sup> by	Larr	y Hartsough (UA Associates) / Al	an Crockett (Self)			
	Discussion	Non	e.				
		11 <b>\</b>	-0 N; Motion passed.				

			[Negative is related persuasive.] > 1/3	d and	Is a technical change recommended?		Y	GO TO "Address by Technical Change Option" subsection
	Result of Vote (check one)		[Negative is related persuasive.] < 2/3	d and not	(check one)		N	GO TO "Final" subsection → (E)
		X	X 2/3 ≤ [Negative is related and not persuasive.] < 90% 90% ≤ [Negative is related and not persuasive.] GO TO "Not Significant Finding Control of the cont					
					inding Option" subsection			
			(A)	Withdrawn	(counted under	h in d	lispo	osition)
			(B)	Not related	elated (counted under i in disposition)			osition)
	(check if	X	(C)	Related and not persuasive (significant)		t)		
Fina	applicable)		(D)	Not significant (counted under j in disposition)			sposition)	
<u> </u>						nd persuasive and not I by technical change		DOCUMENT FAILS
			(F)	Addressed	by technical chan	ige (c	oun	ted under k disposition)
	(check if applicable)	X	Comment generate	ted. See Section V-(ii) Comment #1.				

#### **Disposition of Voting Interest Reject 1**

Check only when the Document has not been failed.

1	Original	num	per (#) of Negatives	(g)		
0	Number	of N	egatives withdrawn	gatives withdrawn (h)		
0	Number	of N	egatives found not related	(i)		
0	Number of Negatives found not significant			(j)		
0		Number of Negatives addressed by technical change (Negative becomes not significant)			(k)	
			g - (h + i + j + k) = 0	Reject is Not Valid and denominator of § VI. A	is not included in the pproval Conditions Check	
	Final	X	g - (h + i +j + k) >0	Reject is included in the Approval Conditions Condition		
			Reject without a Negative	Not Valid		

Note: If all of the Negatives included with a Reject Vote are withdrawn, determined to be not related, or determined to be not significant, the Reject Vote is not valid. (*Regulations* ¶ 9.4.3.3)

Note: A Negative addressed by a technical change is automatically considered to be not significant. (*Regulations* ¶ 9.6.1.4.5.2)

# **IV. Other Technical Issues**

#### None

Note: TC Chapter may choose to address a technical issue that is not part of a Negative received on a Letter Ballot (i.e., a Comment or a reason not addressed by a Vote response) by handling it as a Negative and finding it related and technically persuasive. The TC Chapter may then fail the Document or address such technical issue by using the procedure defined in *Regulations* § 9.6.1.4.3 to make a technical change to the Document. (*Regulations* ¶ 9.6.1.4.2.5)

# **V. Comments**

V- (i) Voters' Comments
Commenter 1 (Hirokazu Tsunobuchi/Keyence) - Comment 1

ISO16022 by mutual agreement ISO 29158						
by mutual agreement						
by mutual agreement						
by mutual agreement						
by mutual agreement by mutual agreement by mutual agreement by mutual agreement						
by mutual agreement by mutual agreement by mutual agreement						
by mutual agreement by mutual agreement						
by mutual agreement						
3						
ISO 29158						
155 27156						
The TC Chapter agreed to do one of the following actions.  Taskforce Recommendation (unanimous hand vote) Line 2-7.5: Change from 'Dimension of ID mark 'window' to 'field'  *No motion is required in this step.  Already addressed by Commenter #, Comment #						
VI. Editorial Changes Other						
all sentence are required in						

#### FROM: Section/Paragraph

#### **Line 2-7.5**

	•••				
	•	2-7.4	race for ID Mark	(specify): Front Face [ ], Kear Face [ ]	
		2-7.5	Dimensions of ID Mark Window	Width = 680 μm Height = 680 μm	by mutual agreement
			C: 4- T45 C C		

#### Table 2

•			
	<u>l</u> f	Distance of the Center of the Left Fiducial from the y-Axis of the Coordinate System	
	my	Distance of the top of the ID Mark Window from the Chord	2-7.3
	mh	Height of the ID Mark Window	2-7.5
	mw	Width of the ID Mark Window	2-7.5
	0	Grid Opening Width	2-2.9
		0 ( 10)	221

#### Figure 1

**Editorial Changes** 

1

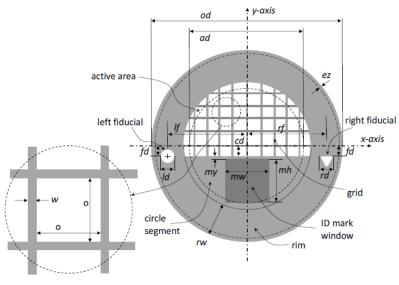


Figure 1
Drawing of Grid Lamella Carrier as Viewed from Front Face

#### 8.1.4.2

8.1.4.2~ Dimensions, of ID Mark Window — The mark shall be located within a window of width  $mw = 680~\mu m$  and a height of  $mh = 680~\mu m$ .

#### 8.1.4.3

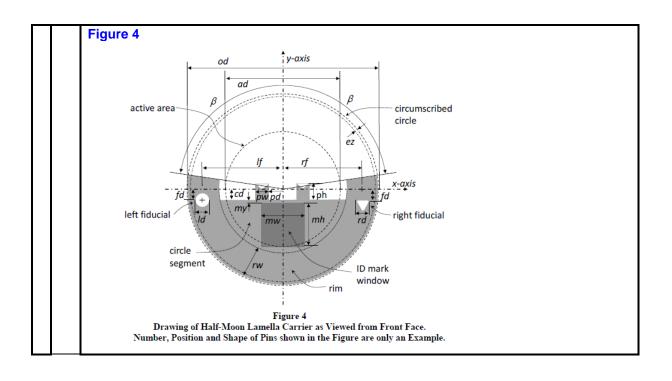
8.1.4.3 Location — The mark window shall be positioned on the circle segment. The window shall be symmetric with respect to the y-axis and shall be below the chord by the distance  $my = 25 \mu m$ . The DMC itself shall be completely within the mark window and the active area.

#### 8.1.4.4

8.1.4.4 Face for ID Mark Window — The face the ID mark is located shall conform to the face as specified in the purchase order.

#### Note 1

NOTE 1: With a dot size of 30  $\mu$ m 10  $\times$  10, 12  $\times$  12 and 16  $\times$  16 dot matrices fit in the ID mark window.



#### TO: Section/Paragraph

#### Line 2-7.5

Ĺ	 <u>- :::</u>		(-F)/		
	2-7.5	Dimensions of ID Mark WindowField	Width = 680 μm Height = 680 μm	by mutual agreement	
Γ		Cida I anoth of Canaca			

#### Table 2

	Coordinate System	
my	Distance of the top of the ID Mark Field Window from the Chord	2-7.3
mh	Height of the ID Mark Window Field	2-7.5
mw	Width of the ID Mark Window Field	2-7.5
0	Grid Opening Width	2-2.9

#### Figure 1

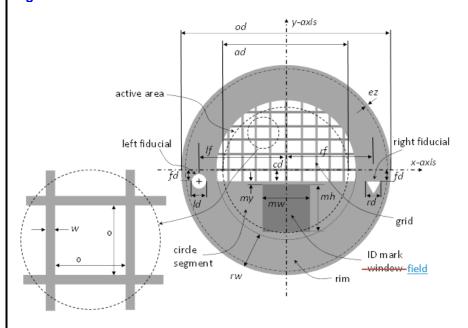


Figure 1
Drawing of Grid Lamella Carrier as Viewed from Front Face

#### 8.1.4.2

8.1.4.2 Dimensions, of ID Mark Window-Field — The mark shall be located within a window-field of width  $mw = 680 \mu m$  and a height of  $mh = 680 \mu m$ .

#### 8.1.4.3

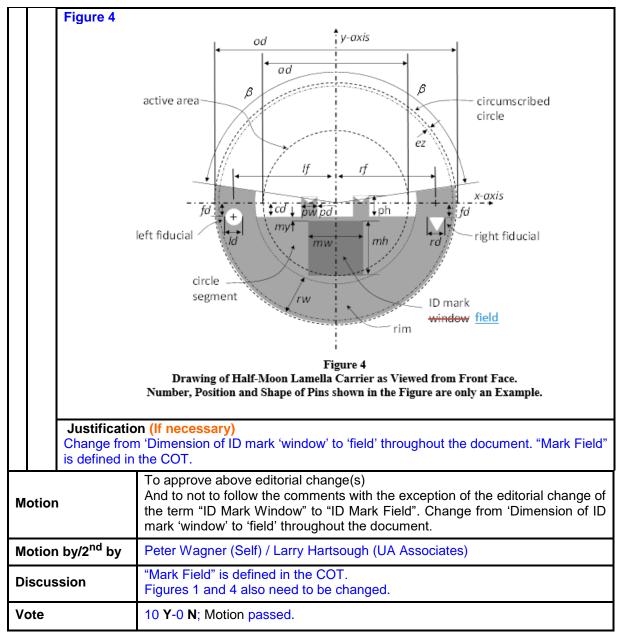
8.1.4.3 Location — The mark window-field shall be positioned on the circle segment. The window-field shall be symmetric with respect to the y-axis and shall be below the chord by the distance  $my = 25 \mu m$ . The DMC itself shall be completely within the mark window-field and the active area.

#### 8.1.4.4

8.1.4.4 Face for ID Mark Window— The face the ID mark is located shall conform to the face as specified in the purchase order.

#### Note 1

NOTE 1: With a dot size of 30  $\mu m$  10  $\times$  10, 12  $\times$  12 and 16  $\times$  16 dot matrices fit in the ID mark <u>fieldwindow</u>.



This table is needed for each Comment accompanied a Vote

Commenter 2 (Tsuyoshi Onishi/Hitachi Ltd.) - Comment 1

\*TF/TC Chapter to fill in section/paragraph #, if necessary.

We decide to accept this SEMI draft document 6311A.

But there is more appropriate expression for some terms and items in "2-7 ID Marking". We would like to expect that these items will be corrected.

2-7. ID M	-7. ID MARKING					
2-7.1	Туре	<del>2-dim square DMC</del> Data Matrix (2D code)	ISO16022			
2-7.3	Position	Distance from Chord: 25 µm	by mutual agreement			
2-7.4	Face for ID Mark	(specify): Front Face [], Rear Face []	by mutual agreement			
2-7.5	Dimensions of ID Mark Window Exclusion zone for ID Mark	Width = 680 μm Height = 680 μm	<del>by mutual agreement</del>			
2-7.6	Side Length of Square Dot#3,#4	Target[] ± Tolerance[] μm	by mutual agreement			
2-7.7	Dot Depth #3,#4	Target[] ± Tolerance[] μm	by mutual agreement			
2-7.8	Marking Quality#4	Better than grade C according to ISO 29158	ISO 29158			
2-7.9	Content of ID Mark	(specify according to ISO 16022, ECC200):_				

<sup>#3</sup> Target values aiming at a Mark Grade better than C according to ISO 29158 #4 Specify either according to lines 2-7.6 and 2-7.7 or according to line 2-7.8

#### The TC Chapter agreed to do one of the following actions.

Taskforce Recommendation (unanimous hand vote)
Line 2-7.5: Change from 'Dimension of ID mark 'window' to 'field'

\*No motion is required in this step.

X	Already addressed by Commenter 1, Comment #1
	No further action was taken by the TC Chapter.
	Refer to the TF for more consideration.
	New Business
	Editorial Change

## Commenter 3 (Kyoichiro Asayama/JEOL) - Comment 1

\*TF/TC Chapter to fill in section/paragraph #, if necessary.

We accept this SEMI draft document 6311A.

But there is more appropriate expression for some terms and items in '2 7 ID Marking'. We would like to expect that these items will be corrected.

2-7. ID M	2-7. ID MARKING						
2-7.1	Туре	2 dim square DMC Data Matrix (2D code)	ISO16022				
2-7.3	Position	Distance from Chord: 25 μm	by mutual agreement				
2-7.4	Face for ID Mark	(specify): Front Face [], Rear Face []	by mutual agreement				
2-7.5	Dimensions of ID Mark Window Exclusion zone for ID Mark	Width = 680 μm Height = 680 μm	by mutual agreement				
2-7.6	Side Length of Square Dot#3,#4	Target [] ± Tolerance [] μm	by mutual agreement				
2-7.7	Dot Depth #3,#4	Target [] ± Tolerance [] μm	by mutual agreement				
2-7.8	Marking Quality#4	Better than grade C according to ISO 29158	ISO 29158				
<del>2-7.9</del>	Content of ID Mark	(specify according to ISO 16022, ECC200):_					

<sup>#3</sup> Target values aiming at a Mark Grade better than C according to ISO 29158

#### The TC Chapter agreed to do one of the following actions.

Taskforce Recommendation (unanimous hand vote)

Line 2-7.5: Change from 'Dimension of ID mark 'window' to 'field'

#### \*No motion is required in this step.

**Editorial Change** 

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X	Already addressed by Commenter 1, Comment #1
	No further action was taken by the TC Chapter.
	Refer to the TF for more consideration.
	New Business

# V-(ii) Comments Created by Handling Negative

Comment (Created by Handling Negative) NC - 1

	*TF	/TC Chapter to fill in				
Comment	The usage of footnotes in section 7 is wrong and not in accordace with the Style Manual. As the footnote doesn't provide reference to outside SEMI material or trademark owner information. They should be expressed by using NOTE following each section needs an explanation by a description in NOTE.  It seems the TF leader/author confuse the requirement of using footnote in a Figure or Table.					
	Th	e TC Chapter agreed to do one of the following actions.				
	Already addressed by Commenter #, Comment #					
Action		No further action was taken by the TC Chapter.				
9		Refer to the TF for more consideration.				
		New business				
	X	Editorial change				

<sup>#4</sup> Specify either according to lines 2-7.6 and 2-7.7 or according to line 2-7.8

	Options	Case 1: No vote in th					
	for		roted on as a group in § VI. Editorial Changes Other				
	editorial change Case 2: Voted in this section:						
	(check						
	one)	Original section num "FROM" and "TO" fie	nber and at least one full sentence are required in elds.				
	FROM: S	Section/Paragraph Section	7.1				
			• 2-4.1 Material(s) of LC				
	• 2-1 1 1	Manufacturing Method	• 2-5.1 Material of Film <sup>3</sup>				
			• 2-5.2 Thickness of Film <sup>3</sup>				
		Form Factor	• 2-5.4 Total Number of Defective Sites in Zones A, B and C <sup>3</sup>				
	• 2-2.5	Thickness	• 2-5.5 Missing Film Area <sup>3</sup>				
	• 2-2.7 I	Edge Profile	• 2-5.6 Surface Roughness <sup>3</sup>				
	• 2-2.9 (	Grid Bar Width³	• 2-6.1 Particulate Contamination <sup>4</sup>				
	• 2-2.9 (	Grid Opening Width <sup>3</sup>	• 2-6.2 Surface Roughness <sup>4</sup>				
	• 2-2.12	Number of Pins <sup>4</sup>	• 2-7.4 Face for the ID Mark				
	• 2-2 12	Distance of Pins from y-Axis <sup>4</sup>	• 2-7.6 Side Length of Square Dot <sup>5</sup>				
		Width of Pin <sup>4</sup>	• 2-7.7 Depth of Dot <sup>5</sup>				
			• 2-7.8 Marking Quality <sup>5</sup>				
		Height of Pin <sup>4</sup>	• 2-7.9 Content of ID Mark				
	• 2-2.16	Shape of the Pins					
			<sup>5</sup> Either dot size and depth or marking quality shall be included in the purchase order.				
ш	3 Applies only	u to grid I C	This is a Draft Document of the SEMI international Standards program. No material on this page is to be c Permission is granted to reproduce and/or distribute this document, in whole or in part, only within the scope of activity. All other reproduction and/or distribution without the prior written consent of SEMI is prohibited.				
dito		y to half-moon LC	Page 3				
rial (	TO: Sect	ion/Paragraph Section 7.1					
<u> </u> ဌူ							
שו עש			• 2-4.1 Material(s) of LC				
ng	• 211	Manufacturing Method	• 2-5.1 Material of Film <sup>3</sup>				
Editorial Changes		Manufacturing Method	<ul> <li>2-5.1 Material of Film³</li> <li>2-5.2 Thickness of Film³</li> </ul>				
nges	• 2-1.2 I	Form Factor	<ul> <li>2-5.1 Material of Film³</li> <li>2-5.2 Thickness of Film³</li> <li>2-5.4 Total Number of Defective Sites in Zones A, B and C³</li> </ul>				
nges	• 2-1.2 I • 2-2.5 T	Form Factor Thickness	<ul> <li>2-5.1 Material of Film³</li> <li>2-5.2 Thickness of Film³</li> </ul>				
nges	<ul><li>2-1.2 I</li><li>2-2.5 I</li><li>2-2.7 I</li></ul>	Form Factor Thickness Edge Profile	<ul> <li>2-5.1 Material of Film³</li> <li>2-5.2 Thickness of Film³</li> <li>2-5.4 Total Number of Defective Sites in Zones A, B and C³</li> <li>2-5.5 Missing Film Area³</li> </ul>				
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nges	• 2-1.2 I • 2-2.5 T • 2-2.7 I • 2-2.9 G • 2-2.12 • 2-2.13 • 2-2.13 • 2-2.16   *Applies only  *Applies only  *Applies only  *Applies only	Form Factor Thickness Edge Profile Grid Bar Width³ Grid Opening Width³ Number of Pins⁴ Distance of Pins from y-Axis⁴ Width of Pin⁴ Height of Pin⁴ Shape of the Pins  y to grid LC y to half moon LC  tion (If necessary)	<ul> <li>2-5.1 Material of Film³</li> <li>2-5.2 Thickness of Film³</li> <li>2-5.4 Total Number of Defective Sites in Zones A, B and C³</li> <li>2-5.5 Missing Film Area³</li> <li>2-5.6 Surface Roughness³</li> <li>2-6.1 Particulate Contamination⁴</li> <li>2-6.2 Surface Roughness⁴</li> <li>2-7.4 Face for the ID Mark</li> <li>2-7.6 Side Length of Square Dot⁵</li> <li>2-7.7 Depth of Dot⁵</li> <li>2-7.8 Marking Quality⁵</li> <li>2-7.9 Content of ID Mark</li> <li>3-Either dot size and depth or marking quality shall be included in the purchase order.</li> </ul> This is a Draft Document of the SEMI International Standards program. No material on this page is to be core Permission is granted to reproduce and/or distribute this document, in whole or in part, only within the scope of SEI activity. All other reproduction and/or distribution without the prior written consent of SEMI is prohibited.				

Motion	To approve above editorial change(s)
Motion by/2 <sup>nd</sup> by	Larry Hartsough (UA Associates) / Alan Crockett (Self)
Discussion	Motion is justified because the information is already contained in the acceptable Table Footnote(s).
Vote	11 Y-0 N; Motion passed.

This table is needed for each Comment created by handling Negative.

# VI. Editorial Changes Other than Those Voted on in § V None other than listed in previous section.

# VII. Approval Conditions Check VII. - (i). Approval Rate

APPROVAL CONDITION 1: All Negatives have been discussed and were withdrawn, found not related, found not persuasive, or addressed by a technical change. (*Regulations* ¶ 9.6.2.1.2)

APPROVAL CONDITION 2: At least 90% of the sum of valid Voting Interest Accept and Voting Interest Reject Votes must be Accept. (*Regulations* ¶ 9.6.2.1.3)

Note: If both approval conditions are not satisfied, the Document fails.

		Accepts		(Accepts + Valid Rejects)			
Approval Rate	=	37	1	38	=	97.4%	≥90%

# VII. – (ii) Approval Level (check one)

Note: See Regulations § 9.6.2 for further information.

Globally Approved (No Ratification Ballot needed):

The Letter Ballot meets the Letter Ballot approval conditions for the global technical committee.

### **Need a Ratification Ballot:**

The Letter Ballot meets the Letter Ballot approval conditions for the TC Chapter and a Ratification Ballot will be issued to validate technical changes.

VIII. Safety Check
Note: See Regulations § 15 for further information.

	X	TI is	nis is not a s still technica	s is not a Safety Document, when all safety-related information is removed, the Document till technically sound and complete. ( <i>Regulations</i> ¶ 8.7.1)					
Motion	This is a Safety Document, when all safety-related information is removed, the Docume technically sound and complete. (Regulations ¶ 8.7.2)								
	Safety Checklist ( <i>Regulations</i> ¶ 15.3) is complete and has been included with the throughout the balloting process. ( <i>Regulations</i> ¶ 15.1.2)								
	Motion by/2 <sup>nd</sup> by			Troy Morrison (Thermo Fisher Scientific) / Alan Crockett (Self)					
	Discussion			None.					
	Vote			9 Y-XX N; Motion passed or failed					

IX. Intellectual Property (IP) Check
Note: This Letter Ballot may cover all or part of a Standard or Safety Guideline. Regardless of the coverage, this IP check applies to the entire Standard or Safety Guideline\*. See Regulations § 16 for further information.

2	X	The TC Chapter meeting chair asked those participating, if they were aware of any patented technology that might be relevant (see <i>Regulations</i> ¶ 16.3.1.1) to the Standard or Safety Guideline; or, any copyrighted items or trademarks that are used/reproduced (see <i>Regulations</i> ¶ 16.4.1.2) in the Standard or Safety Guideline. (Also see, <i>Regulations</i> § 8.8)					
		X	The question is NOT answered in affirmative (No potentially material patented technology or use/reproduction of copyrighted items/trademarks is known.)	GO TO SECTION X.			
			The question is answered in affirmative	Is any of the known IPs a patented		Yes, at least one of them is a patented technology	GO TO IX (a) "Patented Technology" subsection
				technology?		No	GO TO IX (b) "Copyright items" subsection

# X. Action for This Document

X This Docu	This Document passed TC Chapter review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.				
Motion by/ 2 <sup>nd</sup> by	Alan Crockett (Self) / Troy Morrison (Thermo Fisher Scientific)				
Discussion	None.				
Vote	9 Y-0 N				
Final Action	X Motion passed				
i iliai Action	Motion failed				

Note: If the use of PMPT or copyrighted item is justified by the TC Chapter, LOA or release form must be received before publication can proceed.